



Where is the Destination of the Packaging Technology?

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We know the smart phone market is the major element in semiconductor industry shifting from the computing market in terms of Si node advancement and wafer scale packaging technology. Smartphone itself has generated the concept of connectivity which has provoked related markets like GPU/Network/Memory where solutions of packaging technology have ever been paid critical attention. On top of it, Internet of things(IoT) has been a hot potato in the industry where package integration is becoming a key concept.

In this talk, the trend of markets according to packaging technologies will be reviewed and followed by major movements or stream of 'paradigm shift' in packaging technologies. Lastly, what is going to happen in future will be discussed.

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